Sheet_L of _1 FORM PTO 1449 (modified)			ATTY DOCKET NO. SERV		ERIAL NO.	RIAL NO	
U.S. DEPARTMENT OF COMMERCE			259/014	V073,173			
			APPLICANT Gu Sung KIM				
			FILING DATE February 13, 2002		GROUP 2814		
			U.S. PATENT DOCUMENTS				
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			FOREIGN PATENT DOCUMENT	s			
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	0	THER DOCUME	NT(S) (Including Author, Title, Oate,	Pertinent Pages, E	tc.)		
18		KOHL, Paul A.; MARTIN, Kevin, "Wafer-Level Packaging Addresses Chip-to-Module Interconnections"					
<u></u>	Semiconductor International, CAHNERS Business Information, Reed Elsevier, Inc. (April 2)						
18		KOHL, Paul A., et al, "Air-Gaps for Electrical Interconnections": Electrochemical and Solid-State					
<u> </u>		Letters, 1	Letters, 1(1):49-51, The Electrochemical Society, Inc. (1998)				
		 					
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"EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.